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(54) Title: POWER MODULE PACKAGE WITH MOLDED VIA AND DUAL SIDE PRESS-FIT PIN

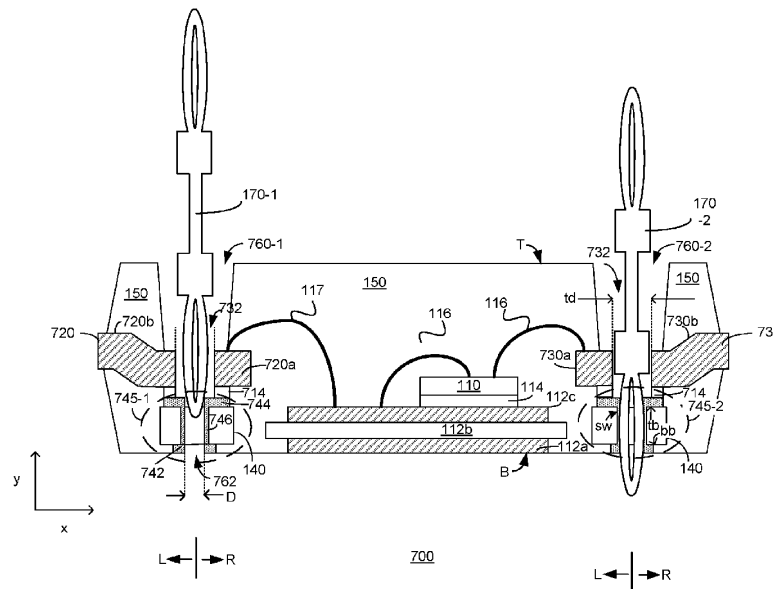


FIG. 7

(57) Abstract: A module (100, 700) includes an assembly of a semiconductor device die (110) coupled to a lead frame (120, 130, 720, 730). A board (150) is disposed below the lead frame. The board includes a plated-through hole (PTH) (162, 762) aligned with an opening (132, 732) in the lead frame above the board. The module further includes a mold body (150) encapsulating at least a portion of the assembly. The mold body (150) includes a through-mold via (TMV) (160, 760-1, 760-2) aligned with the opening in the lead frame and with the PTH (162, 732). The PTH is physically accessible from outside the mold body through the TMV (160, 760-1, 760-2) and the opening in the lead frame.

[Continued on next page]

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